

3761

Patent Application
Attorney Docket No: 687-401



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Snitkin et al.
Serial No.: 09/939,098
Filed: August 24, 2001
For: Coated Sling Material

Group Art Unit: 37

Examiner: Anderson

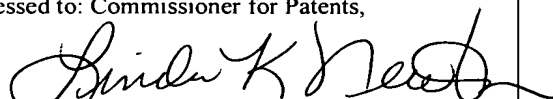
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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, DC 20231 on:

March 14, 2003

Date


Signature - Linda K. Newton

THIRD SUPPLEMENTAL
INFORMATION DISCLOSURE STATEMENT

#10

Commissioner for Patents and Trademarks
Washington, DC 20231

Sir:

Pursuant to 37 C.F.R. 1.97 and 1.98, enclosed for consideration by the Examiner during examination of the above identified application are copies of the following documents listed on the attached form PTO-1449.

Applicants assert that nothing herein is intended to be construed as an admission as to whether a document constitutes prior art against the present application. Applicants reserve the right, pursuant to 37 C.F.R. 1.131, 1.132 or otherwise, to establish that the document(s) are not "prior art". Applicants have provided these documents to comply with their duty under 37 C.F.R. 1.56.

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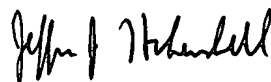
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Also enclosed for the Examiner's consideration is a copy of packaging for a Prolene Soft product (2 pages) available from Ethicon.

Please charge the 37 CFR Section 1.17(p) fee of \$180.00 to Deposit Account No 501921 for the submission of this supplemental information disclosure statement. Please charge any additional fees required for the timely submission of this supplemental information disclosure statement to that Deposit Account.

In view of the foregoing, consideration and allowance of this application are respectfully requested.

Respectfully submitted,



Jeffrey J. Hohenshell

Registration Number 34,109

Date: March 14, 2003

Enclosures